ASSOCIATION CONNECTING	Material Composit © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved utions.	under both	This docum level parts, t	ent is a declarat the declaration of	ion of the su	ubstances s all lower	within the manufacture level materials for w	rer listed it which the m	em. Note: anufacture	if the item is an as r has engineering	sembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Informa	ation													
Company name* Company unique ID				que ID		Unique ID Authority			Response Date*					
nsemi											2023-06-08			
Contact Name			Title - Contact				Phone - Contact*			Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*			Email - Representative*				
Product-Env-Stewar	rds		Product Envir	oduct Enviro Compliance NA Product-Env-Stewards@o				vards@onsemi.co	ls@onsemi.com					
Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	ective Date Version Manufacturing Site		Ianufacturing Site	V	Veight*	UOM	Unit Type		
		AR0143 A0-DRB	ATSC00XUE R	1MP 1/4 CIS			2023-06-08		Ν	1Y5	1	97.96	mg	Each
Ianufacturing P	Proccess Information	n												
Terminal Plating / Grid Array Material Terminal Base Al			lloy	J-STD-020 MS	L Rating	Peak Proc	ess Body T	emperatur	e Max Time at Peak	Temperatu	ire Num	ber of Reflow Cyc	les	
SnAgCu CU Alloy 3					260		С	30	second	ls 3				
omments														
TTENTION: MSL	3 Rated item requires Ba	ake and D	ry Pack (after	electrical test)										
or more information	n regarding material com	position	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	28.5	mg		Misc.	proprietary data		0.1083	mg
			Supplier	Silicon (Si)	7440-21-3		28.1096	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2822	mg
Die Attach	0.97	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.3638	mg
			Supplier	Ethylene Glycol	107-21-1		0.0097	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0291	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.2037	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3638	mg
Imaging Lens	34.8	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.8315	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.8315	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.8315	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1834	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.8315	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.8315	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		25.459	mg
Lid Attach	1.75	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.525	mg
			Supplier	Filler (SiO2)	68909-20-6		0.0875	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.5687	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.5687	mg
Iold Compound-Black	45.67	mg		Phenolic Resin	proprietary data		6.8505	mg
			Supplier	Oxirane	39817-09-9		6.8505	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.3701	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4567	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.2288	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.9134	mg
older Ball	33.42	mg	Supplier	Silver (Ag)	7440-22-4		1.0026	mg
			Supplier	Tin (Sn)	7440-31-5		32.2503	mg
			Supplier	Copper (Cu)	7440-50-8		0.1671	mg
ubstrate and Solder Mask	52.39	mg	Supplier	Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane	105391-33-1		0.5868	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		6.7897	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0786	mg

			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	1.2207	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.5868	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.3039	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0052	mg
			Supplier	Acetophenone Derivative	Proprietary Data	1.8284	mg
			Supplier	Carbon Black (C)	1333-86-4	0.3039	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.3039	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	6.2868	mg
			В	Nickel (Ni)	7440-02-0	0.7387	mg
			Supplier	Gold (Au)	7440-57-5	0.0262	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.6621	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.5868	mg
			Supplier	Copper (Cu)	7440-50-8	19.6253	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	9.4564	mg
Wire Bond - Au	0.46	mg	Supplier	Gold (Au)	7440-57-5	0.46	mg